

8/16-bit Data Bus Flash Memory Card

MF82M1-G7DATXX
MF84M1-G7DATXX
MF88M1-G7DATXX
MF810M-G7DATXX
MF816M-G7DATXX
MF820M-G7DATXX

Connector Type

Two-piece 68-pin

DESCRIPTION

The MF8XXX-G7DATXXX is a flash memory card which uses eight-megabit flash electrically erasable and programmable read only memory IC's as common memory and a 64-kilobit electrically erasable and programmable read only memory as attribute memory.

- Program/erase operation by software command control
- Program/erase voltage 12V (common memory)
- 100,000 program/erase cycles
- Write protect switch

FEATURES

- 68 pin JEIDA/PCMCIA
- 8 /16 controllable data bus width
- Buffered interface
- TTL interface level

APPLICATIONS

- Notebook computers
- Printers
- Industrial machines

PRODUCT LIST

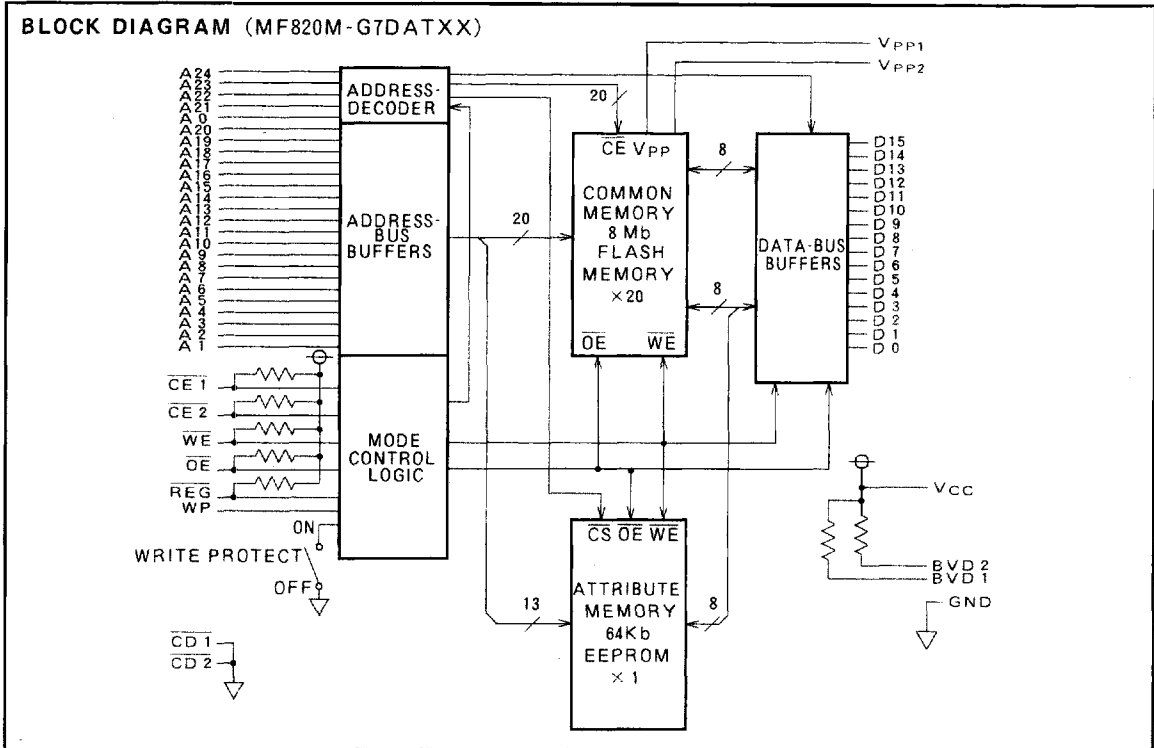
Type name	Item	Memory capacity	Data bus width (bits)	Access time (ns)	Number of pins	Outline drawing
MF82M1-G7DATXX		2MB	8 /16	200	68	68P-002
MF84M1-G7DATXX		4MB				
MF88M1-G7DATXX	★★	8MB				
MF810M-G7DATXX	★★	10MB				
MF816M-G7DATXX	★★	16MB				
MF820M-G7DATXX	★★	20MB				

★★ : Under development

FLASH MEMORY CARDS

PIN ASSIGNMENT

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	35	GND	Ground
2	D 3	Data I/O	36	CD 1	Card detect 1
3	D 4		37	D11	Data I/O
4	D 5		38	D12	
5	D 6		39	D13	
6	D 7		40	D14	
7	CE 1	Card enable 1	41	D15	
8	A10	Address input	42	CE 2	Card enable 2
9	OE	Output enable	43	NC	No connection
10	A11	Address input	44	NC	
11	A 9		45	NC	
12	A 8		46	A17	Address input
13	A13		47	A18	
14	A14		48	A19	
15	WE	Write enable	49	A20	
16	NC	No connection	50	A21	
17	VCC	Power supply voltage	51	VCC	Power supply voltage
18	VPP 1	Programming supply voltage 1	52	VPP 2	Programming supply voltage 2
19	A16	Address input	53	A22	A22 (NC for ≤ 4 MB types)
20	A15		54	A23	A23 (NC for ≤ 8 MB types)
21	A12		55	A24	No connection
22	A 7		56	NC	
23	A 6		57	NC	
24	A 5		58	NC	No connection
25	A 4		59	NC	
26	A 3		60	NC	
27	A 2		61	REG	Attribute memory select
28	A 1		62	BVD 2	Battery voltage detect 2
29	A 0	63	BVD 1	Battery voltage detect 1	
30	D 0	Data I/O	64	D 8	Data I/O
31	D 1		65	D 9	
32	D 2		66	D10	
33	WP	Write protect	67	CD 2	Card detect 2
34	GND	Ground	68	GND	Ground



FUNCTIONAL DESCRIPTION

The operating mode of the card is determined by five active low control signals (\overline{REG} , $\overline{CE1}$, $\overline{CE2}$, \overline{OE} , \overline{WE}), three supply voltages (V_{CC} , V_{PP1} , V_{PP2}) and control registers located in each memory IC.

Common memory function

When the \overline{REG} signal is set to a high level common memory is selected.

Read only mode

When the voltages applied to both V_{PP1} and V_{PP2} are less than the voltage applied to V_{CC} (i.e. $V_{PP} = 0V$ to V_{CC}), the control registers of each memory IC are set to read only mode.

Operation of the card then depends on the four possible combinations of $\overline{CE1}$ and $\overline{CE2}$ (note \overline{WE} should be set to a high level when the device is in read only mode except during combination (4) where it's condition is unimportant) :

(1) If $\overline{CE1}$ is set to a low level and $\overline{CE2}$ is set to a high level, the card will work as an eight bit data

bus width card. Data can be accessed via the lower half of the data bus (D0 to D7).

(2) If both $\overline{CE1}$ and $\overline{CE2}$ are set to a low level, data will be accessible via the full sixteen bit data bus width of the card. In this mode LSB of address bus (A0) is ignored.

(3) If $\overline{CE1}$ is set to a high level and $\overline{CE2}$ is set to a low level the odd bytes (only) can be accessed through upper half of the data bus (D8 to D15). This mode is useful when handling the odd (upper) bytes in a sixteen bit interface system. Note that A0 is also ignored in this operating condition.

(4) If $\overline{CE1}$ and $\overline{CE2}$ are set to a high level, the card will be in standby mode where it consumes low power. The data bus is kept high impedance.

When \overline{OE} is set to a low level data can be read from the card, depending on the address applied and the setting of $\overline{CE1}$ and $\overline{CE2}$ as mentioned above, except under combination (4).

FLASH MEMORY CARDS

When \overline{OE} is set to a high level and \overline{WE} is set to a high level the card is in an output disable mode and the data bus will be in a high impedance state regardless of the condition of $\overline{CE1}$ and $\overline{CE2}$.

Read/write mode

When a programming voltage (V_{PPH}) is applied to either or both of V_{PP1} and V_{PP2} , read/write mode is enabled for the corresponding banks of memory IC's inside the card. V_{PP1} enables the Even Byte bank and V_{PP2} enables the Odd Byte bank.

By using the 4 combinations of $\overline{CE1}$ and $\overline{CE2}$ as described under Read only mode above the appropriate Data Out and Command/Data In bus selection can be made.

If \overline{OE} is set to a high level and \overline{WE} set to a low level, the control register will latch command data applied at the rising edge of the \overline{WE} signal. Note that more than one bus cycle may be required to latch the command and/or the related data—please refer to the Command Definition table.

If \overline{OE} is set to a low level and \overline{WE} is set to a high level the card data can be read from the card depending on the condition of the control register.

After latching the command data, the card will go into programming, erasure or other operation mode. For details please refer to the Command Definition table, each individual command's definition and the programming and erasure algorithms.

Attribute memory

When the \overline{REG} signal is set to a low level attribute memory is selected.

The card includes a byte wide attribute memory consisting of 8K bytes of EEPROM located at the even addresses when the card is in the 8 bit operating mode. It is located at sequential addresses on the lower half of the data bus when the card is in 16 bit operating mode i. e. A0 is ignored.

To access the attribute memory, first set $\overline{CE1}$ and $\overline{CE2}$. Set $\overline{CE1}$ to low level and $\overline{CE2}$ to high level for 8 bit mode or $\overline{CE1}$ and $\overline{CE2}$ to low level for 16 bit mode. Then select the required address. Note please take care that in 8 bit mode A0 must be set low for attribute memory access i. e. an even address is applied. In 16

bit mode it is not important whether A0 is high or low. Data can then be read by setting \overline{OE} to a low level with \overline{WE} set to a high level.

Writing to the attribute memory can be achieved in one of two ways, in byte mode or in page mode. The page mode write is a function which allows up to 32 bytes of data to be written in a single cycle. A page is defined as a block of 32 even bytes selected by addresses A6 through A13.

To write to attribute memory set \overline{OE} to high level and \overline{WE} to low level. The data to be written will be latched at the rising edge of \overline{WE} . Then, unless \overline{WE} changes back from high level to low level within 30 μ s an automatic erase/program operation starts which will complete within 10ms.

If \overline{WE} makes a transition back from high to low level within 30 μ s of the first data being latched then further bytes from a page of up to 32 bytes can be latched with further \overline{WE} low to high transitions. The latching operation is repeated until all bytes are loaded at which point holding \overline{WE} high for greater than 30 μ s will initiate execution of a page erase/program operation which will complete within 10ms.

During page write data loading operations all data must be addressed within one 32 byte page i. e. the page address which is selected by A6 through A13 and must remain constant throughout the data load. Please also remember that for attribute memory A0 is not applicable and it should be set to low, even addressing only, in 8 bit mode or ignored for 16 bit mode.

Write protect mode

The card has a write protect switch on the opposite edge to the connector edge. When it is switched on, the card will be placed into a write protect mode, where data can be read from the card but it cannot be written to it. The WP output pin is set to a high level when the card is in write protect mode and V_{CC} is applied. When the card is not in write protect mode the WP output pin is set to a low level when V_{CC} is applied. By reading the state of the WP output the host system can easily check whether the card is in write protect mode or not.

FLASH MEMORY CARDS

FUNCTION TABLE (COMMON MEMORY) READ ONLY MODE

Mode	REG	CE2	CE1	OE	WE	A0	VPP2	VPP1	I/O (D15-D8)	I/O (D7-D0)
Standby	H	H	H	X	X	X	V _{PP} L	V _{PP} L	High-Z	High-Z
Read A (16-bit)	H	L	L	L	H	X	V _{PP} L	V _{PP} L	Odd byte data out	Even byte data out
Read B (8-bit)	H	H	L	L	H	L	V _{PP} L	V _{PP} L	High-Z	Even byte data out
	H	H	L	L	H	H	V _{PP} L	V _{PP} L	High-Z	Odd byte data out
Read C (8-bit)	H	L	H	L	H	X	V _{PP} L	V _{PP} L	Odd byte data out	High-Z
Output disable	H	X	X	H	H	X	V _{PP} L	V _{PP} L	High-Z	High-Z

Note 1 : H = V_{IH}, L = V_{IL}, X = V_{IH} or V_{IL}

FUNCTION TABLE (COMMON MEMORY) READ/WRITE MODE

Mode	REG	CE2	CE1	OE	WE	A0	VPP2	VPP1	I/O (D15-D8)	I/O (D7-D0)
Standby	H	H	H	X	X	X	V _{PP} X	V _{PP} H	High-Z	High-Z
	H	H	H	X	X	X	V _{PP} H	V _{PP} X	High-Z	High-Z
Read A (16-bit)	H	L	L	L	H	X	V _{PP} H	V _{PP} H	Odd byte data out	Even byte data out
Read B (8-bit)	H	H	L	L	H	L	V _{PP} X	V _{PP} H	High-Z	Even byte data out
	H	H	L	L	H	H	V _{PP} H	V _{PP} X	High-Z	Odd byte data out
Read C (8-bit)	H	L	H	L	H	X	V _{PP} H	V _{PP} X	Odd byte data out	High-Z
Write A (16-bit)	H	L	L	H	L	X	V _{PP} H	V _{PP} H	Command or odd byte data in	Command or even byte data in
Write B (8-bit)	H	H	L	H	L	L	V _{PP} X	V _{PP} H	High-Z	Command or even byte data in
	H	H	L	H	L	H	V _{PP} H	V _{PP} X	High-Z	Command or odd byte data in
Write C (8-bit)	H	L	H	H	L	X	V _{PP} H	V _{PP} X	Command or odd byte data in	High-Z
Output disable	H	X	X	H	H	X	V _{PP} H	V _{PP} X	High-Z	High-Z
	H	X	X	H	H	X	V _{PP} X	V _{PP} H	High-Z	High-Z

Note 2 : H = V_{IH}, L = V_{IL}, X = V_{IH} or V_{IL}, V_{PP}X = V_{PP}L or V_{PP}H
To operate refer to the command definition, algorithms and so on.

FUNCTION TABLE (ATTRIBUTE MEMORY)

Mode	REG	CE2	CE1	OE	WE	A0	VPP2	VPP1	I/O (D15-D8)	I/O (D7-D0)
Standby	L	H	H	X	X	X	V _{CC}	V _{CC}	High-impedance	High-impedance
Read A (16-bit)	L	L	L	L	H	X	V _{CC}	V _{CC}	Data out (not valid)	Even byte data out
Read B (8-bit)	L	H	L	L	H	L	V _{CC}	V _{CC}	High-impedance	Even byte data out
	L	H	L	L	H	H	V _{CC}	V _{CC}	High-impedance	Data out (not valid)
Read C (8-bit)	L	L	H	L	H	X	V _{CC}	V _{CC}	Data out (not valid)	High-impedance
Write A (16-bit)	L	L	L	H	L	X	V _{CC}	V _{CC}	Odd byte data in (not valid)	Even byte data in
Write B (8-bit)	L	H	L	H	L	L	V _{CC}	V _{CC}	High impedance	Even byte data in
	L	H	L	H	L	H	V _{CC}	V _{CC}	High impedance	Odd byte data in (not valid)
Write C (8-bit)	L	L	H	H	L	X	V _{CC}	V _{CC}	Odd byte data in (not valid)	High impedance
Output disable	L	X	X	H	H	X	V _{CC}	V _{CC}	High Impedance	High Impedance

FLASH MEMORY CARDS

COMMAND DEFINITION

When either or both V_{PP1} and V_{PP2} are applied the programming voltage (V_{PPH}) the corresponding

memories of the card are set to read/write mode and the operation is controlled by the software command written in the control register.

COMMAND DEFINITION TABLE

Command	Bus cycles	First bus cycle			Second bus cycle			
		Mode	Address	Data in	Mode	Address	Data in	Data out
Read/Reset	1	Write	ZA	FFh (FFFFh)	—	—	—	—
Programme Setup/ Programme	2	Write	PA	40h (4040h)	Write	PA	PD	—
Erase Setup/ Erase Confirm	2	Write	BA	20h (2020h)	Write	BA	D0h (DD00h)	—
Erase Suspend/ Erase Resume	2	Write	BA	B0h (B0B0h)	Write	BA	D0h (D0D0h)	—
Read Status Register	2	Write	ZA	70h (7070h)	Read	—	—	RD
Clear Status Register	1	Write	ZA	50h (5050h)	—	—	—	—
Read Device Identifier Code	2	Write	ZA	90h (9090h)	Read	DIA	—	DID

Note 3. Indicates the basic functions of commands. Refer to the algorithms to operate.

Signal status is defined in function table and bus status.

Parenthesized data shows the data for 16 bit mode operation.

ZA = an address of a memory zone (Please refer to the memory zone)

PA = Programming address

PD = Programming data

BA = An address of a memory block (Please refer to the memory block)

RD = Data of status Register

DIA = Device identifier address

000000h for manufacturer code

000002h for device code

DID = Device identifier data

manufacturer code : 89h (8989h)

device code : A2h (A2A2h)

Read/Reset

The memory in the card is switched to read mode by writing FFh (FFFFh for 16 bit operation) into the control register. This mode is maintained until the contents of register are changed. This mode have nothing to do with the voltage of V_{PP} .

This mode needs to be written to every memory zone to which access is required.

Programme Setup/Programme

The setup programme command sets up the card for programming. It is applied when 40h (4040h for 16 bit operation) is written to control register. Programming will take place automatically after latching the address and data which are applied at the rising edge of \overline{WE} .

The completion of programme can be confirmed by reading status register, after writing Read status register command 70h (7070h for 16 bit operation) to control register.

(For details please refer to the algorithm)

Erase Setup/Erase confirm

The erase setup is a command to set up the memory block for erasure. Writing setup erase command 20h (2020h for 16 bit operation) in the control register followed by erase confirm command D0h (D0D0h for 16 bit operation) will initiate a erasure operation. Erasing will take place automatically after the rising edge of \overline{WE} controlled by a internal timer.

The completion of erase can be confirmed by reading status register, after writing read status register command 70h (7070h for 16 bit operation) to control register.

(For details please refer to the algorithm)

These commands will not erase all the data of a memory card and should be repeated for all the required memory blocks. At an eight bit access mode it should be noticed that the erasure of a memory block will result in odd byte or even byte erasure.

Erase Suspend/Erase Resume

The erase suspend command B0h (B0B0h for 16 bit operation) is a command to generate erase interruption and to read data from another block of selected memory zone.

By writing in the control register erase resume command D0h (D0D0h for 16 bit operation), the memory block will continue the erase operation.

These commands must be executed in erase algo-

rithm.

(For details please refer to the algorithm)

Read Status Register

The Read status register is a command to read the status register's data and to make sure programme or erase operations complete successfully. The data of status register can be read after writing 70h (7070h for 16 bit operation) in the control register. The register's read data is latched on the falling edge of \overline{OE} . At programme or erase, the status register's data must be read to verify the results.

Clear Status Register

The clear status register command will clear data of status register. It is applied when 50h (5050h for 16 bit operation) is written to the control register.

If an error occurred during programme or erase, the status register must be cleared before retrying programme or erase.

Read Device Identifier Codes

The read device identifier codes command is implemented by writing 90h (9090h for 16 bit operation) to the command register. After writing the command, manufacturer code can be read at the address of 000000h of the zone and device code can be read at the address 000002h of the zone. Each card uses the same type of memory throughout and each memory zone will respond the same code.

(Do not apply high voltage to A10 pin in order to try and read the device identifier codes as this will result in the card being destroyed.)

FLASH MEMORY CARDS

STATUS REGISTER

When operating programme or erase, it is necessary to read status register data and to transact

these bit. Each memory IC used in this card has internal status register to make sure programme or erase operations complete successfully.

7 (15) BIT	6 (14) BIT	5 (13) BIT	4 (12) BIT	3 (11) BIT	2 ~ 0 (10 ~ 8) BIT
Programme / Erase Status Bit	Erase Suspend Bit	Erase Error Bit	Programme Error Bit	Vpp Error Bit	Reserved

Note 4. () : for 16 bit operation

Bit ; Field name

7(15) BIT ; Programme/Erase Status Bit
0 = Busy (in programming/erasing)
1 = Ready

6(14) BIT ; Erase Suspend Bit
1 = Erase Suspended

5(13) BIT ; Erase Error Bit
1 = Erase Error

4(12) BIT ; Programme Error Bit
1 = Programme Error

3(11) BIT ; Vpp Error
1 = Error of voltage at Vpp

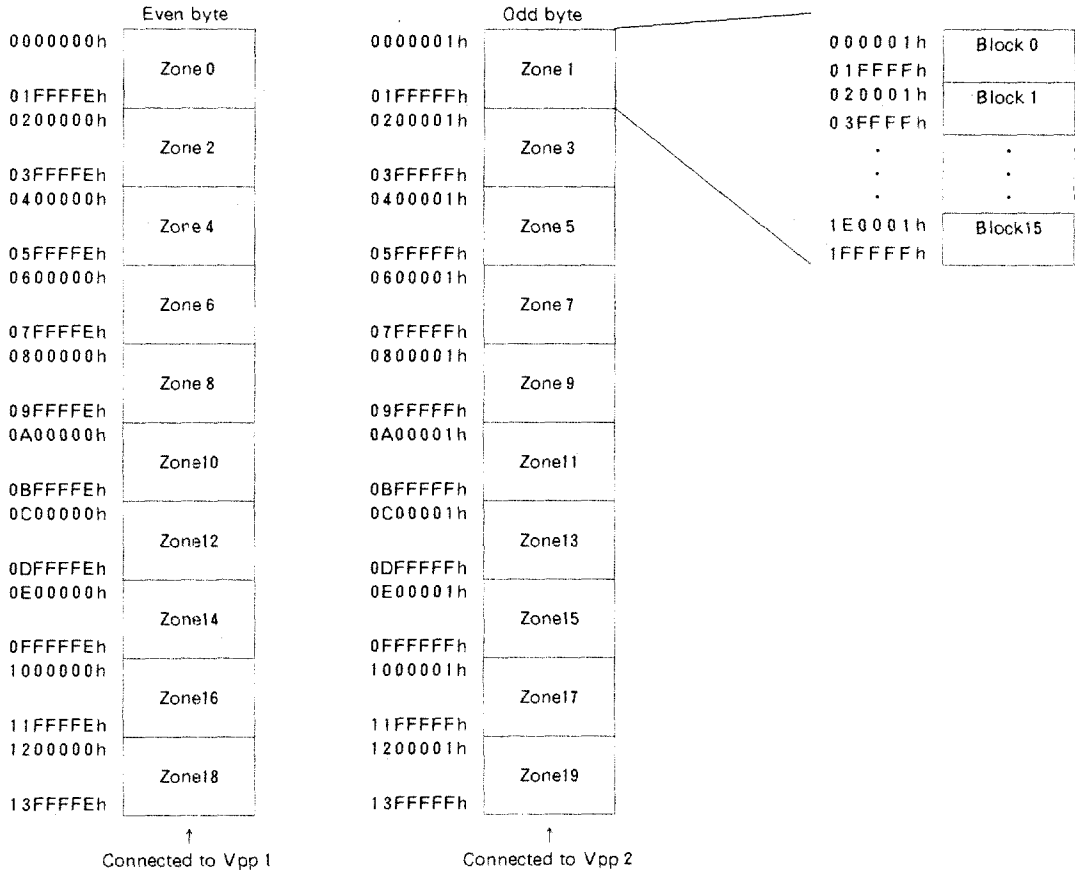
2(10) BIT
{

0(8) BIT ; Reserved for future

MEMORY ZONE AND BLOCK

8 bit mode

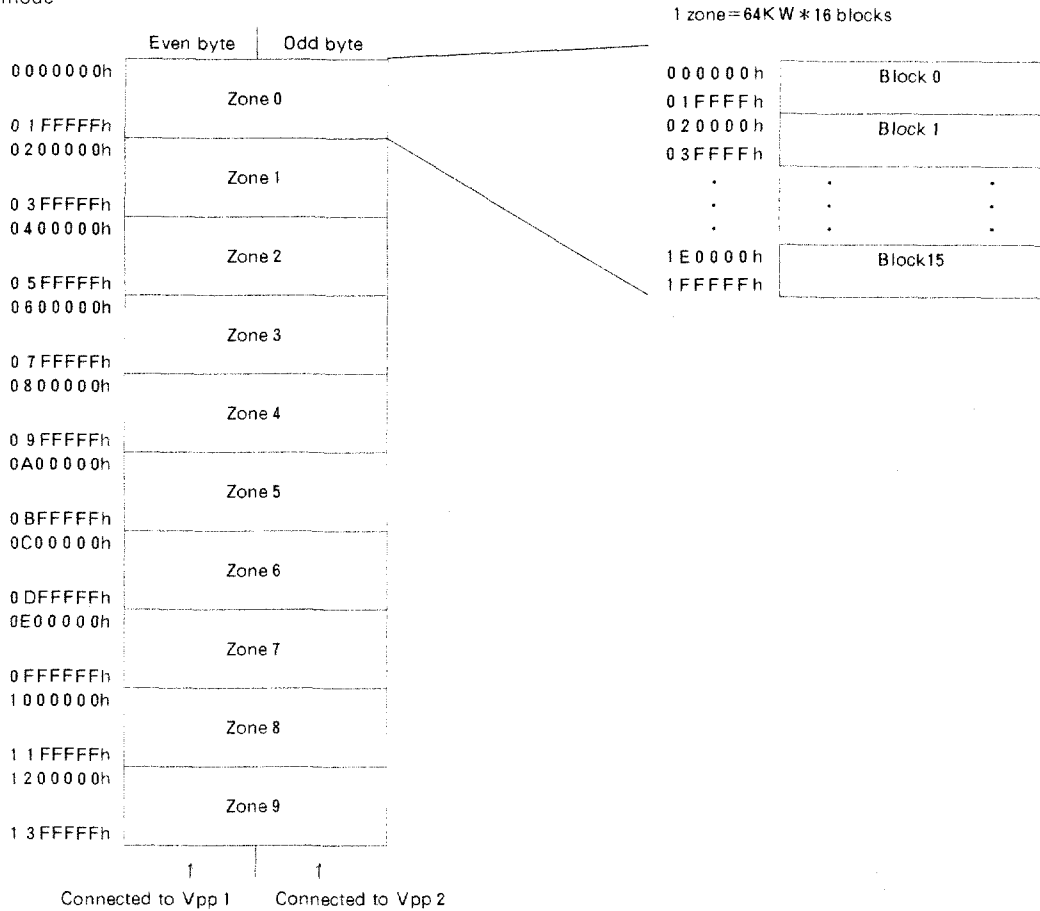
1 zone = 64KB * 16 blocks



Zone 2 to 19 do not exist in 2 MB
 Zone 4 to 19 do not exist in 4 MB
 Zone 8 to 19 do not exist in 8 MB
 Zone 10 to 19 do not exist in 10MB
 Zone 16 to 19 do not exist in 16MB

FLASH MEMORY CARDS

16 bit mode



AD signal is ignored at 16 bit mode.

- Zone 1 to 9 do not exist in 2 MB
- Zone 2 to 9 do not exist in 4 MB
- Zone 4 to 9 do not exist in 8 MB
- Zone 5 to 9 do not exist in 10MB
- Zone 8 to 9 do not exist in 16MB

PROGRAMME SEQUENCE

8 bit Operation

First apply V_{PPH} to V_{PP1} and/or V_{PP2} . Then the write programme setup command (40h) to the address to be programmed. The next write sequence will initiate the programming operation which will end automatically as this period being controlled by an internal timer and the data will be programmed. To make sure that the data is programmed correctly write a read status register command (70h) and read data. (Reading should be waited more than 6 μ s after the programme setup command)

If the data is programmed step address and programme data according to the above sequence.

The next address to be programmed should be written in a memory zone whose V_{PP} voltage is set to V_{PPH} . If not write the reset command (FFh) and then drop the V_{PP} voltage to V_{PPL} .

Then apply V_{PP} for the desired memory zone and proceed with programming.

In applications where V_{PP1} and V_{PP2} are shorted together all addresses can be programmed without there being any need for the programming algorithm to take account of the cards memory zone architecture.

16 bit operation

The algorithm of 16 bit programming is almost same as the 8 bit programming. (Please refer to the algorithm and the status of bus at programming)

ERASE SEQUENCE

ERASE

8 bit Operation

First apply V_{PPH} to V_{PP1} and/or V_{PP2} . Then write the erase setup command (20h) and erase confirm command (D0h) for the applicable block address.

An erasure operation will then commence which will be finished in 1.6s typical or less this being automatically controlled by an internal timer.

To make sure that the data is erased correctly write the read status register command (70h) and read data (Reading should be waited more than 300ms after the erase confirm command). After erasure has been completed write the reset command (FFh) to the control register, set V_{PP1} and/or V_{PP2} to V_{PPL} as applicable and proceed with the erase operation for the next memory block.

16 bit Operation

Most of the algorithm of 16 bit erasure is same as the one of the 8 bit erasure.

(Please refer to the algorithm and the state of bus at erasure.)

ERASE SUSPEND

8 bit Operation

The erase suspend is a command to generate block erase interruption in order to read data from another block of the selected memory zone. It is necessary to write the erase suspend command (B0h) in the erase algorithm. The execution of the erase suspend can be confirmed by reading data of the status register, after writing the read status register command (70h).

Then it is necessary to write the read command (FFh) in control register in order to read data, after reading the status register's data.

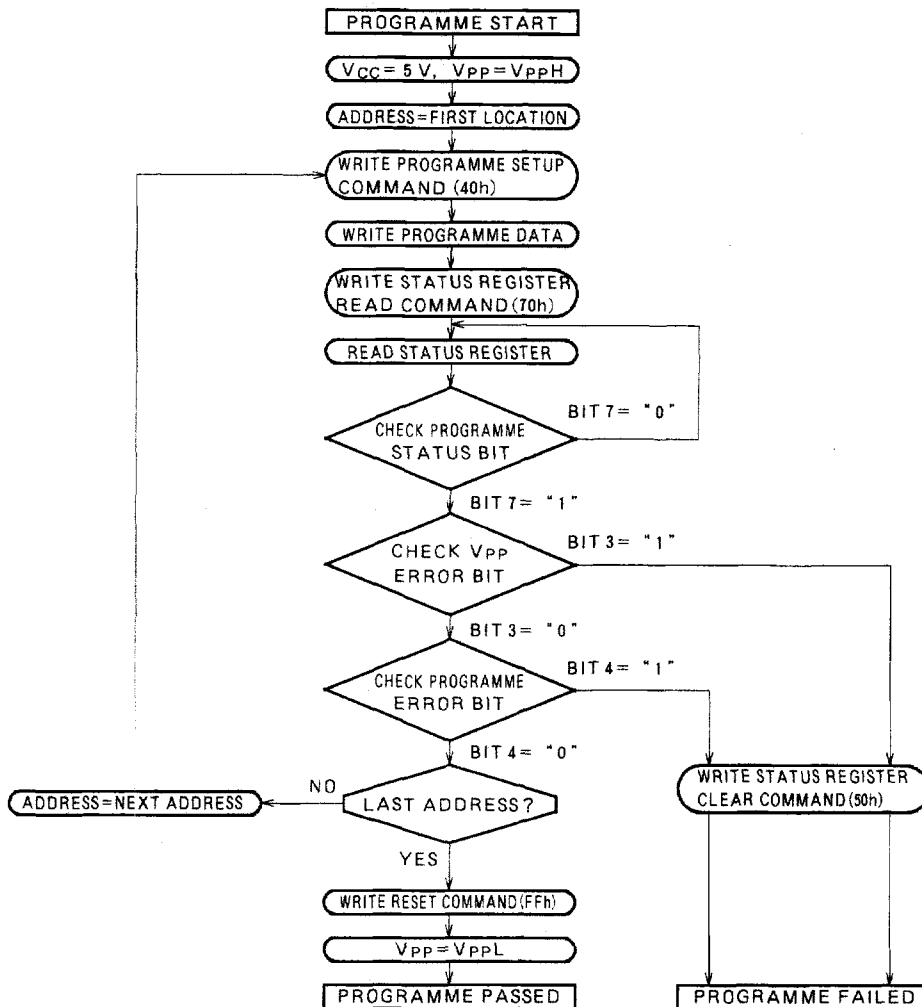
After the erase resume command (D0h) is written in the control register, the memory block will continue erase operation.

16 bit Operation

Most of the algorithm of 16 bit erase suspending is same as the one of the 8 bit erase suspending. (Please refer to the algorithm and the state of bus at erase suspending.)

PROGRAMME ALGORITHM

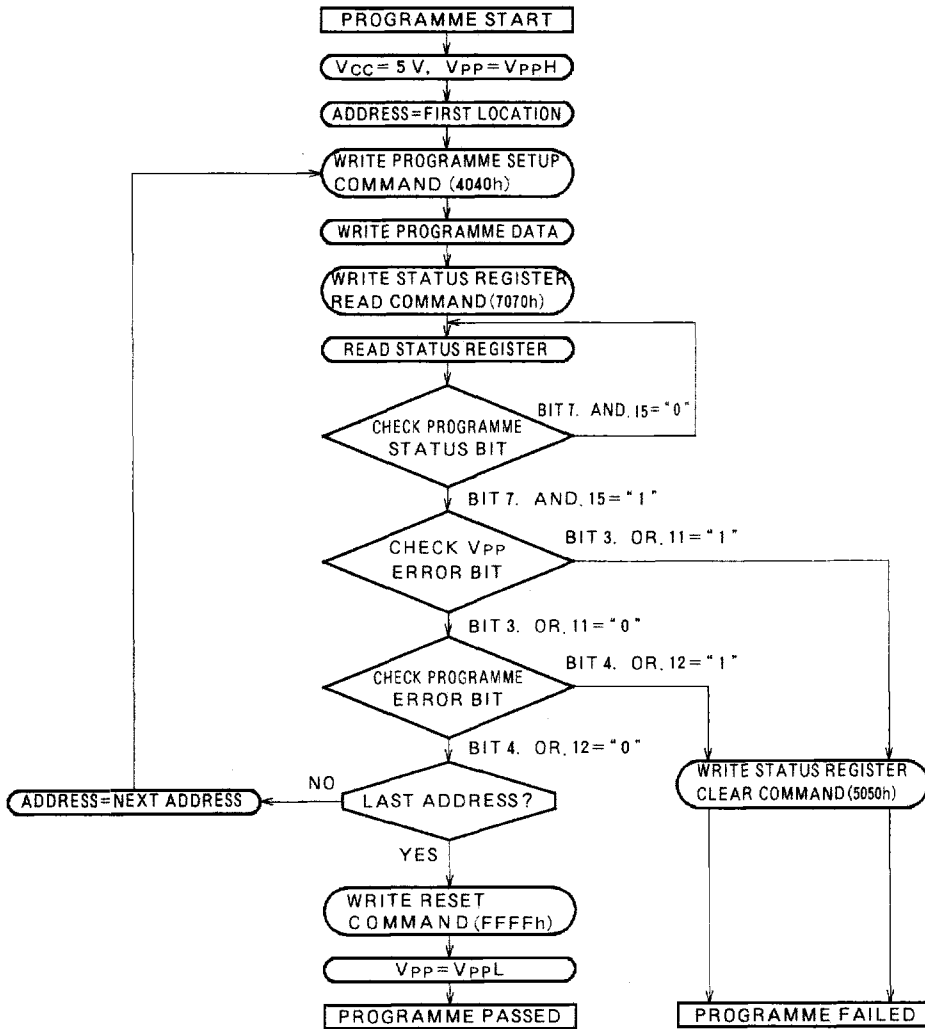
8 bit mode



Note 5. . This is programme algorithm for a memory zone and not for a card.
 . If Vpp error bit is detected, try to programme again at VppH level.

PROGRAMME ALGORITHM

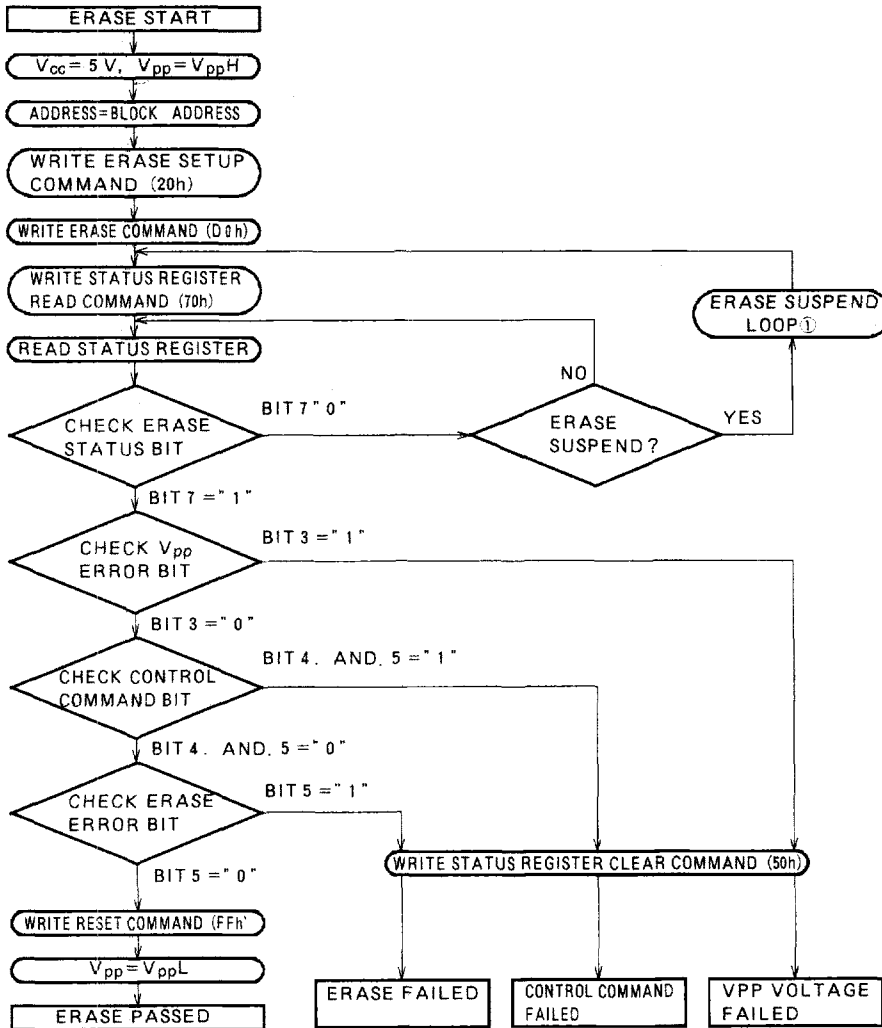
16 bit mode



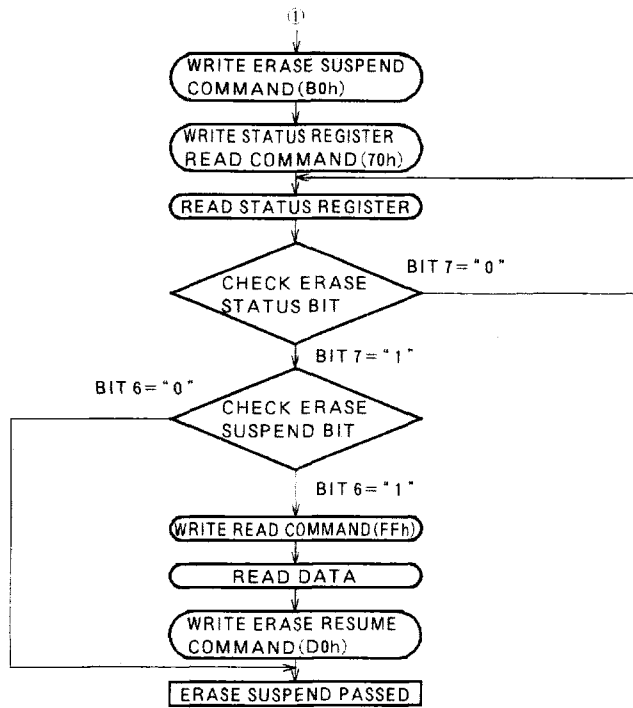
Note 6. If Vpp error bit is detected, try to programme again at VppH level.
 . This is programme algorithm for a memory zone and not for a card.
 ..OR.:=Logical or ; ..AND.:= Logical and

ERASE ALGORITHM

8 bit mode



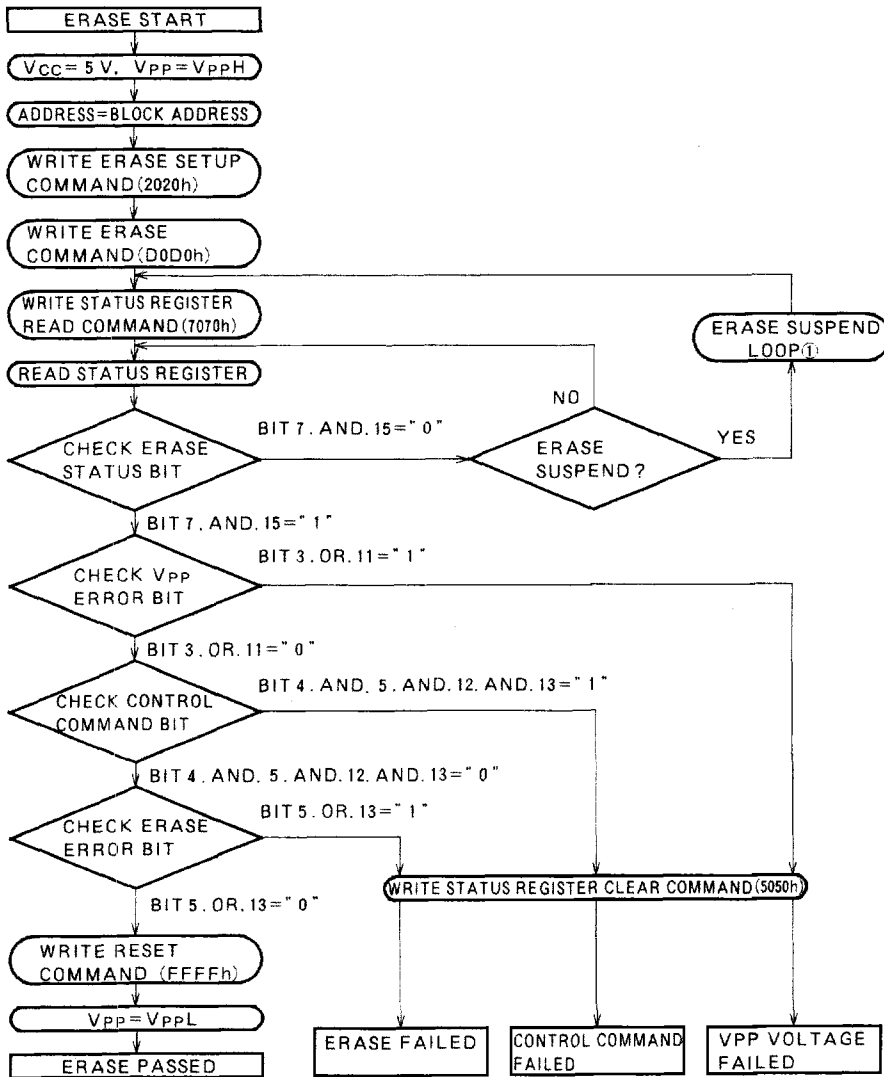
Note 7. If V_{pp} error bit is detected, try to programme again at V_{ppH} level.
 This is an erase algorithm for a memory block and not for a card.
 ..OR. : = Logical or



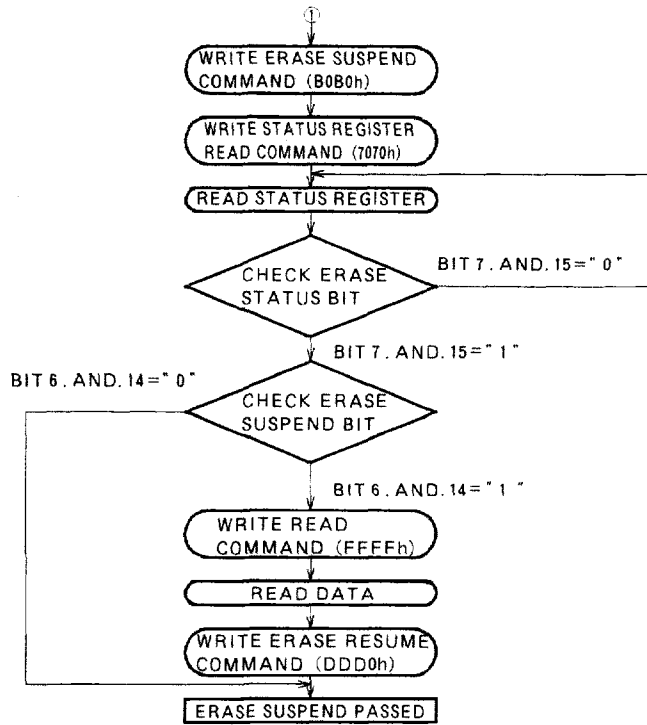
Note 8. Reading data from block other than the suspended block the in zone generating erase suspend.

ERASE ALGORITHM

16 bit mode



Note 9. If Vpp error bit is detected, try to programme again at VppH level.
 . This is an erase algorithm for a memory block and not for a card.
 .. OR. := Logical or ; . AND. := Logical and



Note 10. Reading data from block other than the suspended block the in zone generating erase suspend.
 . AND. : = Logical and

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	V _{CC} Supply voltage	With respect to GND	-0.5~6.0	V
V _{PP}	V _{PP} Supply voltage		-0.5~14.0	V
V _I	Input voltage		-0.3~V _{CC} +0.3	V
V _O	Output voltage		0~V _{CC}	V
T _{opr}	Operating temperature	Read/Write Operation	0~70	°C
T _{stg}	Storage temperature		-40~80	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0 ~ 55°C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
V _{CC}	V _{CC} supply voltage	4.75	5.0	5.25	V
V _{PP} L	V _{PP} supply voltage during READ only mode	0	V _{CC}	V _{CC} +1.0	V
V _{PP} H	V _{PP} supply voltage during READ WRITE mode	11.4	12.0	12.6	V
V _I H	High input voltage	2.4		V _{CC}	V
V _I L	Low input voltage	0		0.8	V
NACT	Number of simultaneous activated memory zones/blocks	Programme		1	Zone
		Erase		1	Block

FLASH MEMORY CARDS

ELECTRICAL CHARACTERISTICS (Ta=0~55°C, VCC=5V±5%, VPP=VPP_L or VPP_H, unless otherwise noted)

Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
V _{OH}	High output voltage	I _{OH} = -0.1mA, BVDn	2.4			V
		I _{OH} = -1.0mA, Other outputs	2.4			
V _{OL}	Low output voltage	I _{OL} = 2mA	0		0.4	V
I _{IH}	High input current	V _I = V _{CC}			10	μA
I _{IL}	Low input current	V _I = 0V	CE ₁ , CE ₂ , OE, WE, REG	-10	-70	μA
			Other inputs		-10	
I _{OZH}	High output current in off state	CE ₁ = CE ₂ = V _{IH} or OE = V _{IH} , V _O (Dm) = V _{CC}			10	μA
I _{OZL}	Low output current in off state	CE ₁ = CE ₂ = V _{IH} or OE = V _{IH} , V _O (Dm) = 0V			-10	μA
I _{CC1-1}	Active VCC supply current 1	CE ₁ = CE ₂ = V _{IL} , Other inputs = V _{IH} or V _{IL} , Outputs = open		100	200	mA
I _{CC1-2}	Active VCC supply current 2	CE ₁ = CE ₂ ≤ 0.2V, Other inputs ≤ 0.2V or ≥ V _{CC} - 0.2V, Outputs = open		90	180	mA
I _{CC2-1}	Standby VCC supply current 1	CE ₁ = CE ₂ = V _{IH} , Other inputs = V _{IH} or V _{IL}	2 MB		9.0	mA
			4 MB		13	
			8 MB		21	
			10MB		25	
			16MB		37	
			20MB		45	
I _{CC2-2}	Standby VCC supply current 2	CE ₁ = CE ₂ ≥ V _{CC} - 0.2V, Other inputs ≤ 0.2V or ≥ V _{CC} - 0.2V	2 MB	0.1	1.2	mA
			4 MB	0.2	1.4	
			8 MB	0.4	1.8	
			10MB	0.5	2.0	
			16MB	0.7	2.6	
			20MB	0.8	3.0	
I _{PP1}	V _{PP} supply current 1 (each V _{PP} pin)	V _{PP} = V _{PP_L} ≤ V _{CC}	2 MB	10	20	μA
			4 MB	20	30	
			8 MB	30	50	
			10MB	40	60	
			16MB	50	90	
			20MB	70	110	
I _{PP2}	V _{PP} supply current 2 (each V _{PP} pin)	V _{PP} = V _{PP_H} (standby, read)	2 MB		0.3	mA
			4 MB		0.5	
			8 MB		0.9	
			10MB		1.1	
			16MB		1.7	
			20MB		2.1	
I _{PP3}	V _{PP} supply current 3 (each V _{PP} pin)	V _{PP} = V _{PP_H} (programme, erase)		10	35	mA

Note 11. Currents flowing into the card are taken as positive (unsigned).
 Typical values are measured at V_{CC} = 5.0V, V_{PP_L} = 5V, V_{PP_H} = 12V, Ta = 25°C.
 The card consumes active current at programming, erasure even if both CE₁ and CE₂ are high level.

FLASH MEMORY CARDS

CAPACITANCE

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
C _i	Input capacitance	V _i =GND, v _i =25mVrms, f=1MHz, T _a =25°C			45	pF
C _o	Output capacitance	V _o =GND, v _o =25mVrms, f=1MHz, T _a =25°C			45	pF

Note 12 : These parameters are not 100% tested.

SWITCHING CHARACTERISTICS (COMMON MEMORY)

Read Cycle (T_a=0~55°C, V_{CC}=5V±5%, V_{PP}=V_{PPH} or V_{PPH}, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{RC}	Read cycle time	200			ns
t _{a(A)}	Address access time			200	ns
t _{a(CE)}	Card enable access time			200	ns
t _{a(OE)}	Output enable access time			100	ns
t _{dis(CE)}	Output disable time (from \overline{CE})			90	ns
t _{dis(OE)}	Output disable time (from \overline{OE})			90	ns
t _{en(CE)}	Output enable time (from \overline{CE})	5			ns
t _{en(OE)}	Output enable time (from \overline{OE})	5			ns
t _{V(A)}	Data valid time after address change	0			ns

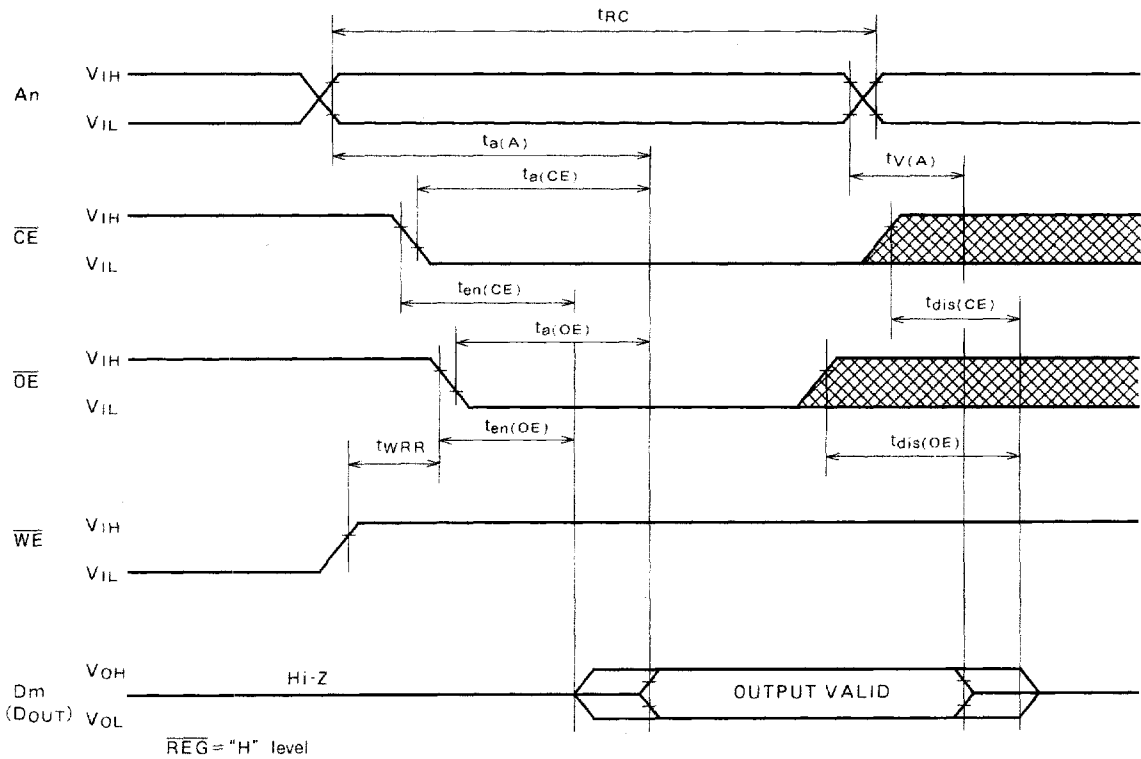
TIMING REQUIREMENTS (COMMON MEMORY)

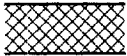
Write Cycle (T_a=0~55°C, V_{CC}=5V±5%, V_{PP}=V_{PPH}, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WC}	Write cycle time	200			ns
t _{AS}	Address setup time	20			ns
t _{AH}	Address hold time	30			ns
t _{DS}	Data setup time	60			ns
t _{DH}	Data hold time	30			ns
t _{WRR}	Write recovery time before read	10			ns
t _{CSE}	Card enable setup time before write	20			ns
t _{CH}	Card enable hold time	30			ns
t _{WP}	Write pulse width	120			ns
t _{WPH}	Write pulse width high	40			ns
t _{DP}	Duration of programming operation	6			μs
t _{DE}	Duration of erase operation	300			ms
t _{VSC}	V _{PP} setup time to card enable low	1			μs
t _{VRW}	V _{PP} recovery time to card enable high	150			ns
t _{Ash}	Address setup time to write enable high	140			ns

Note 13 : Refer to switching characteristics for read parameters

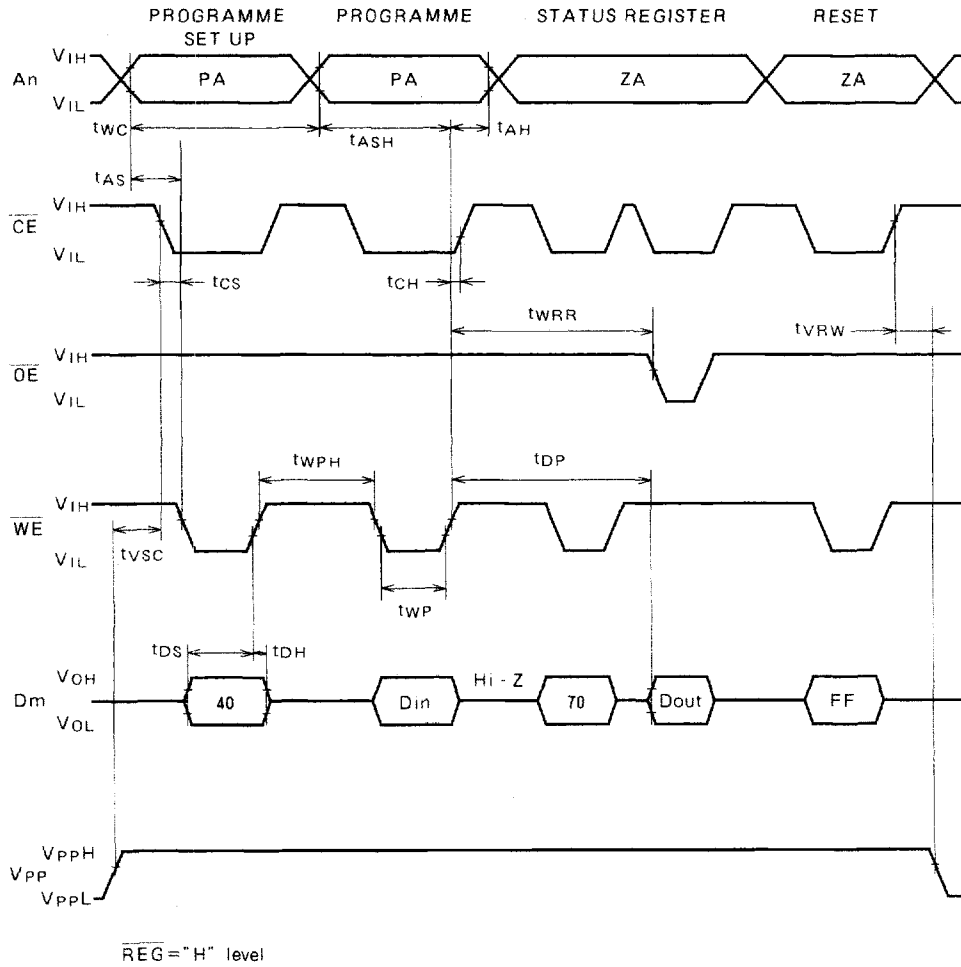
TIMING DIAGRAM
Common Memory Read



Note 14 :  Indicates the don't care input.

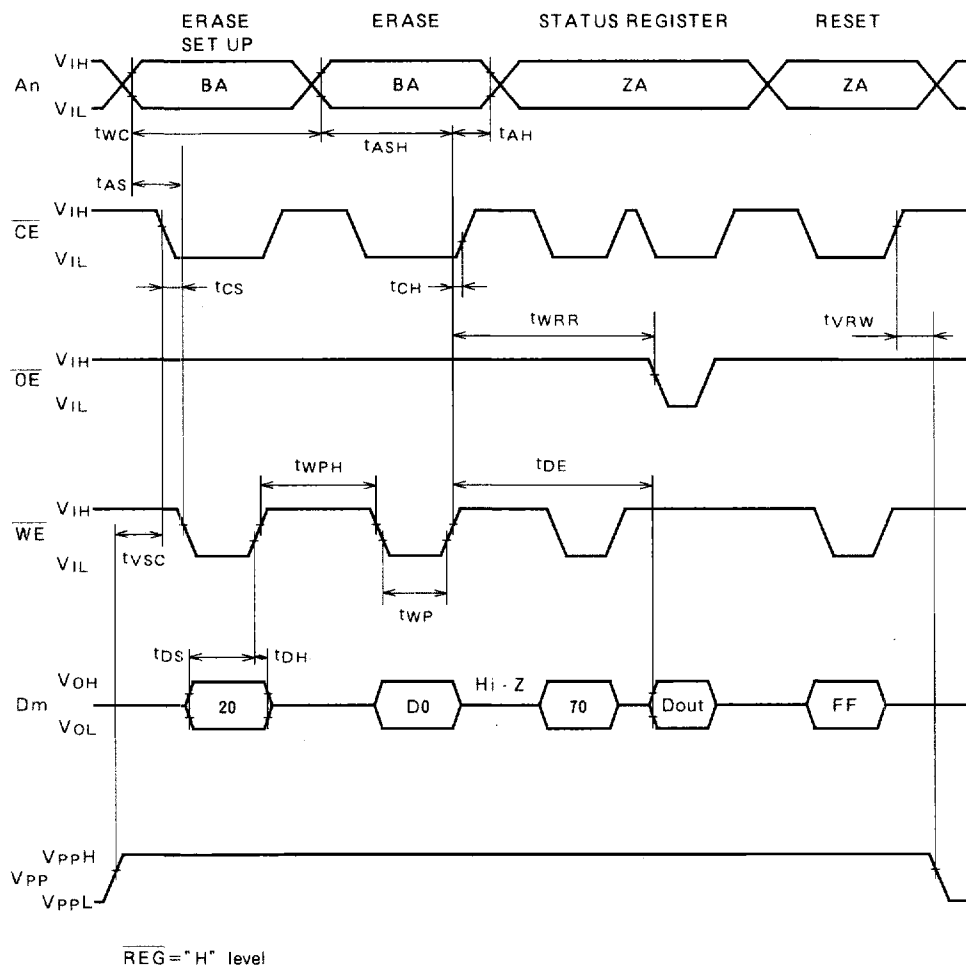
TIMING DIAGRAM (COMMON MEMORY)

Programme Mode



TIMING DIAGRAM (COMMON MEMORY)

Erase Mode



FLASH MEMORY CARDS

SWITCHING CHARACTERISTICS

Read Cycle ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $V_{PP} = V_{CC}$, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t_{RCR}	Read cycle time	300			ns
$t_{a(A)R}$	Address access time			300	ns
$t_{a(CE)R}$	Card enable access time			300	ns
$t_{a(OE)R}$	Output enable access time			150	ns
$t_{dis(CE)R}$	Output disable time (from \overline{CE})			100	ns
$t_{dis(OE)R}$	Output disable time (from \overline{OE})			100	ns
$t_{en(CE)R}$	Output enable time (from \overline{CE})	5			ns
$t_{en(OE)R}$	Output enable time (from \overline{OE})	5			ns
$t_{V(A)R}$	Data valid time after address change	0			ns

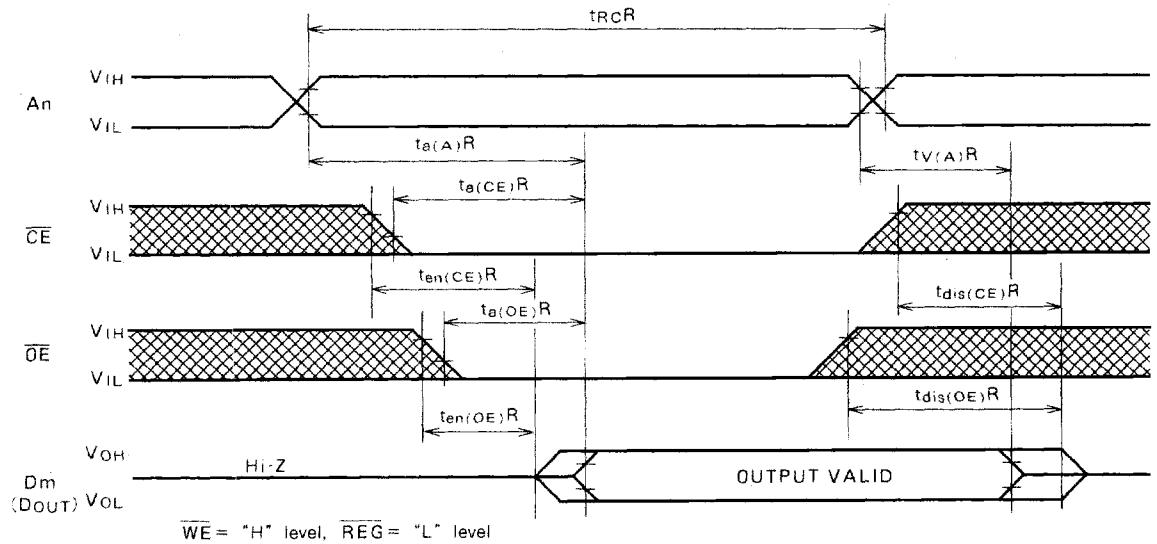
TIMING REQUIREMENTS (ATTRIBUTE MEMORY)

Write Cycle ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5V \pm 5\%$, $V_{PP} = V_{CC}$, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t_{ASR}	Address setup time	30			ns
t_{AHR}	Address hold time	30			ns
t_{CSR}	\overline{CE} setup time	40			ns
t_{CHR}	\overline{CE} hold time	30			ns
t_{DSR}	Data setup time	120			ns
t_{DHR}	Data hold time	40			ns
t_{OESR}	\overline{OE} setup time	30			ns
t_{OEHR}	\overline{OE} hold time	40			ns
t_{WPR}	Write pulse width	170			ns
t_{DLR}	Data latch time	120			ns
t_{BLCR}	Byte load cycle time	0.3		30	μs
t_{WCR}	Write cycle time	10			ms
$t_{en(OE)R}$	Output enable time (from \overline{OE})	5			ns
$t_{dis(OE)R}$	Output disable time (from \overline{OE})	0		100	ns

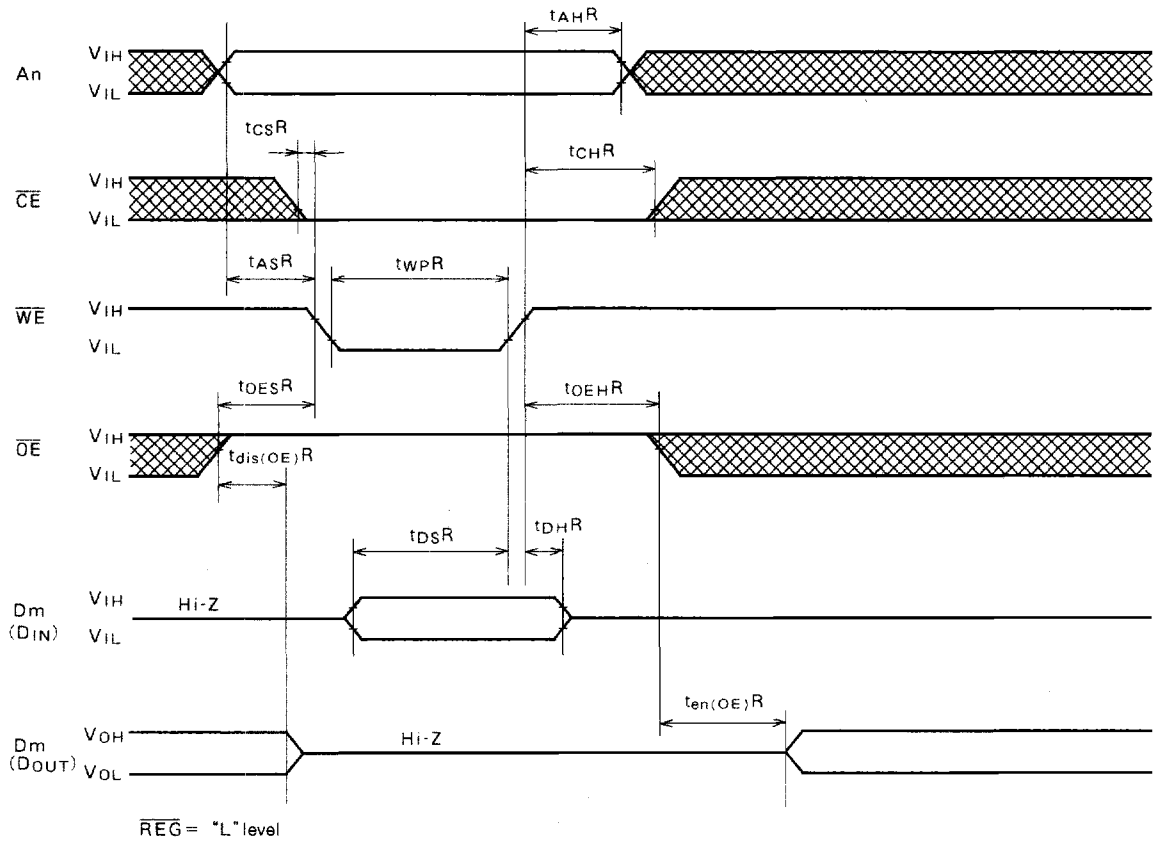
TIMING DIAGRAM (Attribute Memory)

Read

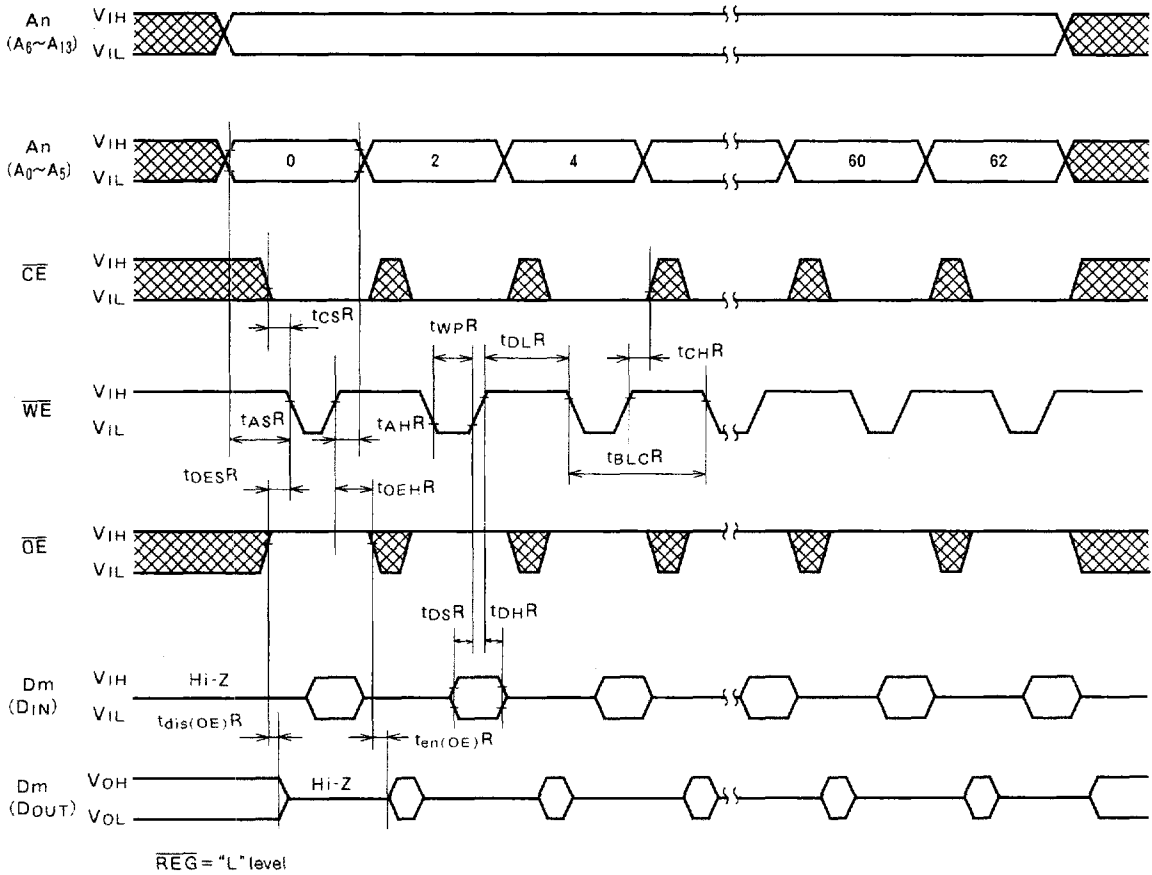


FLASH MEMORY CARDS

Byte Write



Page Mode Write



Note 15 : AC Test Conditions

Input pulse levels : $V_{IL} = 0.4V$, $V_{IH} = 2.8V$

Input pulse rise, fall time : $t_r = t_f = 10ns$

Reference voltage

Input : $V_{IL} = 0.8V$, $V_{IH} = 2.4V$

Output : $V_{OL} = 0.8V$, $V_{OH} = 2.0V$

(t_{en} and t_{dis} are measured when output voltage is $\pm 500mV$ from steady state.)

Load : 100pF + 1 TTL gate

5 pF + 1 TTL gate (at t_{en} and t_{dis} measuring)

16 : The data write is performed during the interval when both \overline{CE} and \overline{WE} are "L" level.

17 : Do not apply inverted phase signal externally when Dm pin is in output mode.

18 : \overline{CE} is indicated as follows :

Read A/Write A : $\overline{CE} = \overline{CE1} = \overline{CE2}$

Read B/Write B : $\overline{CE} = \overline{CE1}$, $\overline{CE2} = \text{"H" level}$

Read C/Write C : $\overline{CE} = \overline{CE2}$, $\overline{CE1} = \text{"H" level}$

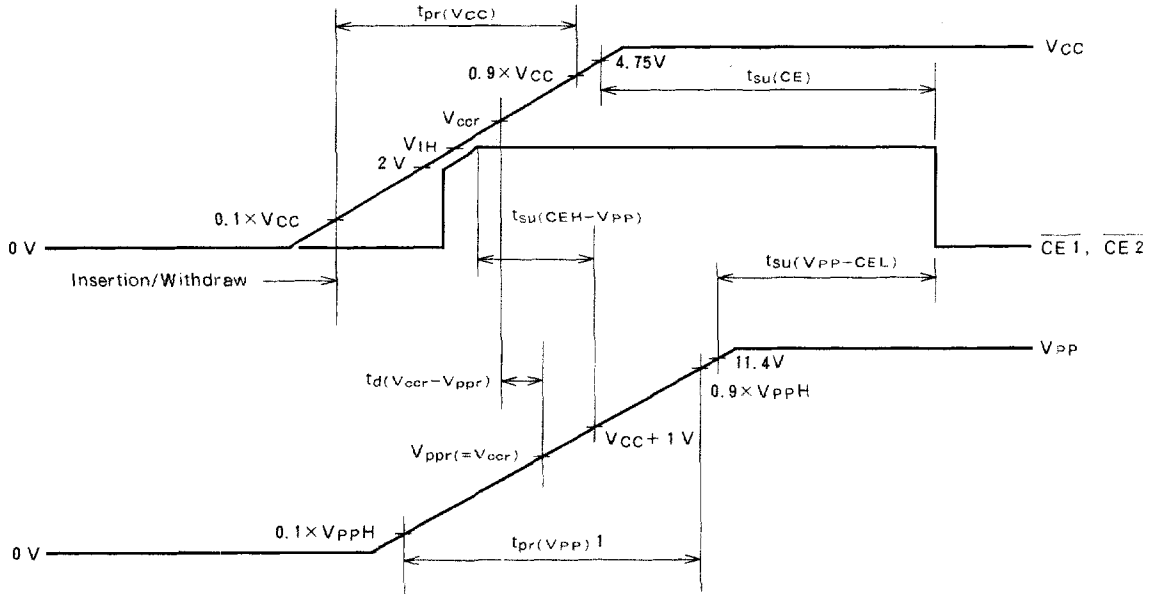
FLASH MEMORY CARDS

RECOMMENDED POWER UP/DOWN CONDITIONS (T_a = 0 ~ 55°C, unless otherwise noted)

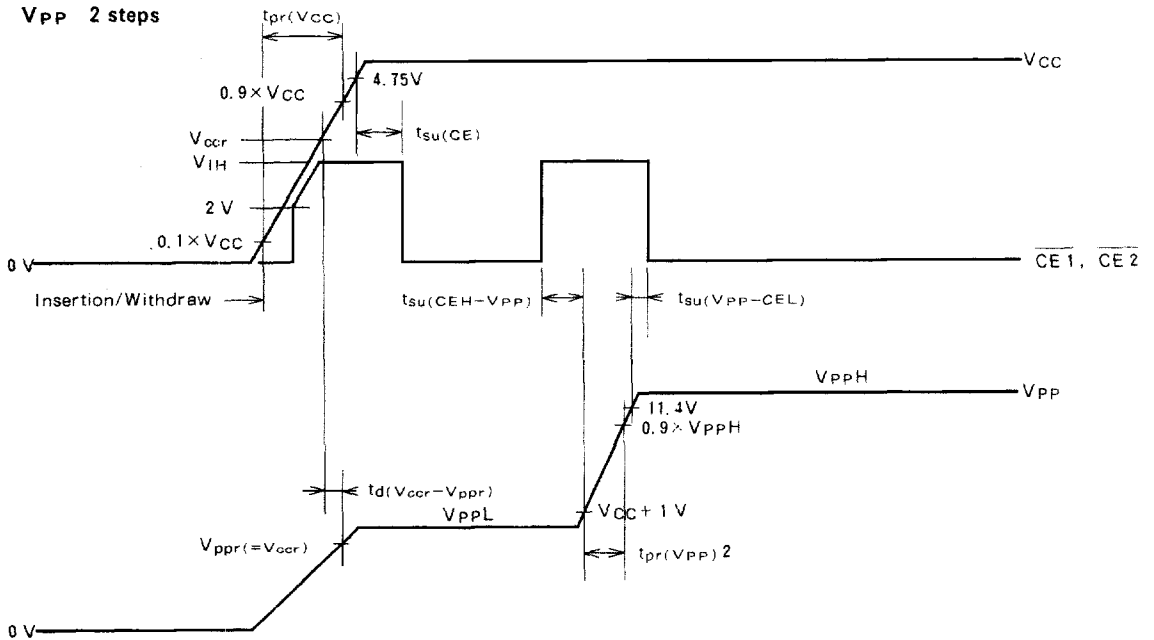
Symbol	Parameter	Conditions	Limits			Unit
			Min.	Typ.	Max.	
V _i (CE)	CE input voltage	0 V ≤ V _{CC} < 2 V	0		V _{CC}	V
		2 V ≤ V _{CC} < 2.4 V	V _{CC} - 0.1	V _{CC}	V _{CC} + 0.1	V
		2.4 V ≤ V _{CC}	2.4		V _{CC} + 0.1	V
t _{su} (CE)	CE setup time		1			ms
t _{rec} (CE)	CE recovery time		1			μs
t _{pr} (VCC)	VCC rise time		0.1		300	ms
t _{pf} (VCC)	VCC fall time		3		300	ms
t _{su} (CEH-VPP)	Setup time before VPP rise		0.15			μs
t _{su} (VPP-CEL)	Setup time after VPP rise		1			μs
t _{rec} (CEH-VPP)	Recovery time before VPP fall		0.15			μs
t _{rec} (VPP-CEL)	Recovery time after VPP fall		1			μs
t _{pr} (VPP) 1	VPP rise time 1		0.24		300	ms
t _{pf} (VPP) 1	VPP fall time 1		7.2		300	ms
t _{pr} (VPP) 2	VPP rise time 2		0.1		300	ms
t _{pf} (VPP) 2	VPP fall time 2		3		300	ms
t _d (VCCr-VPPr)	VPPr delay time after VCCr	0 V ≤ V _{CC} ≤ 4.75 V	0			μs
t _d (VPPf-VCCf)	VCCf delay time after VPPf	0 V ≤ V _{CC} ≤ 4.75 V	0			μs

POWER UP TIMING DIAGRAM

V_{PP} 1 step



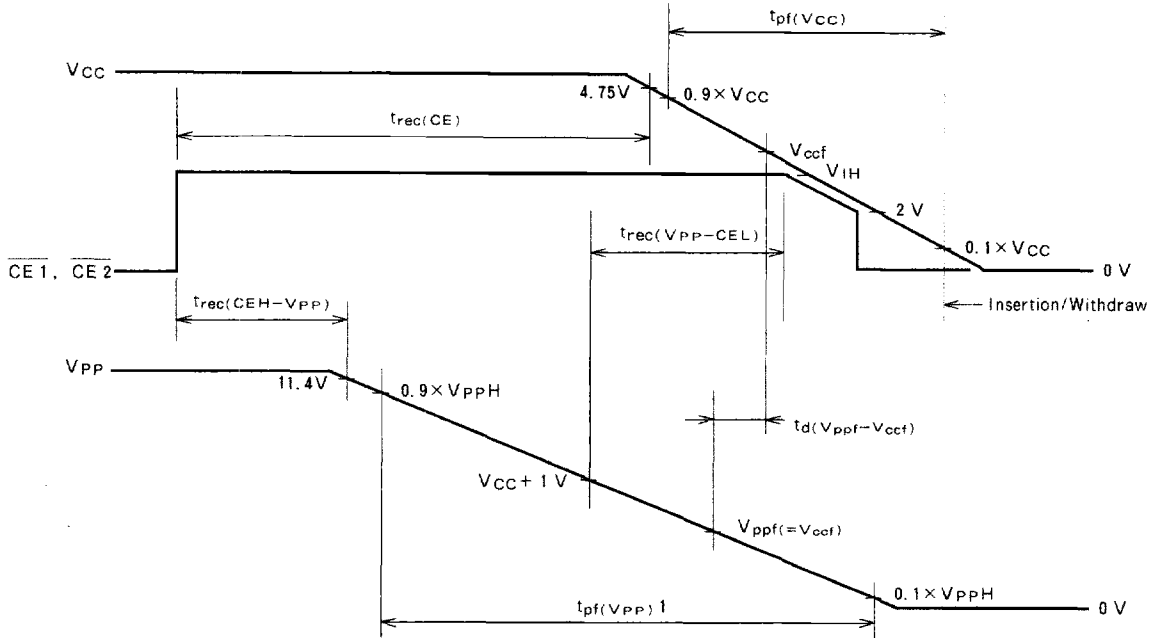
V_{PP} 2 steps



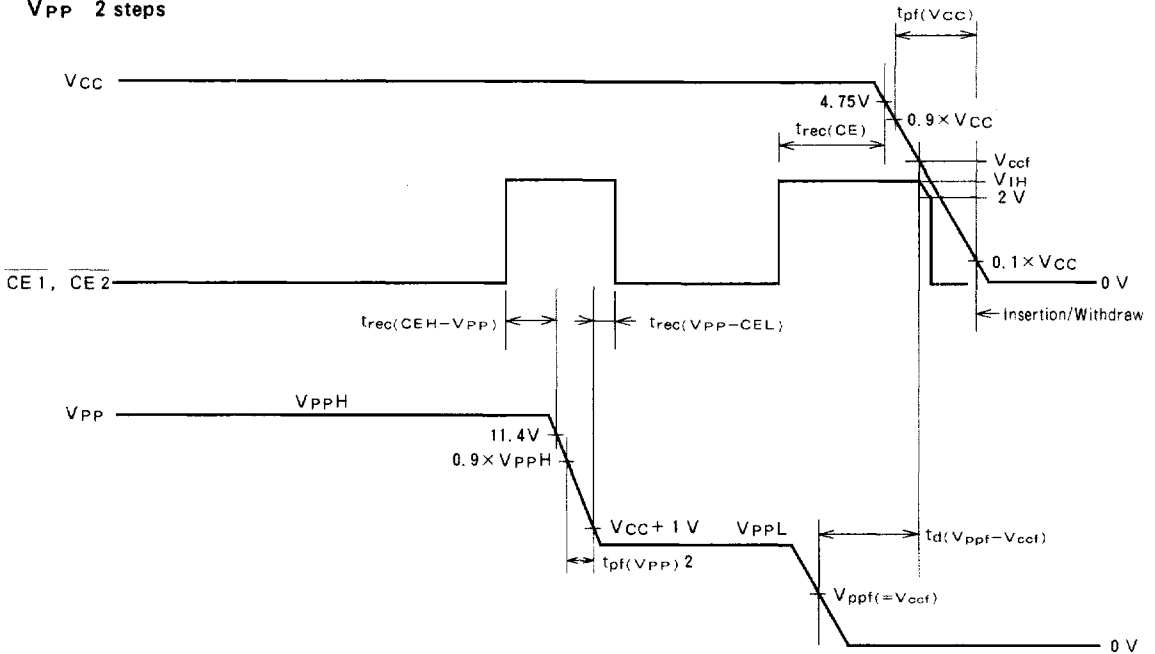
Note 19 : V_{CCr} and V_{PPr} (= V_{CCr}) indicates any voltage when V_{CC} voltage is in the range of 0 V to 4.75V

POWER DOWN TIMING DIAGRAM

V_{PP} 1 step



V_{PP} 2 steps



Note 20 : V_{ccf} and V_{ppf} (= V_{ccf}) indicates any voltage when V_{CC} voltage is in the range of 0 V to 4.75 V

BLOCK PROGRAM/ERASE TIME

Parameters	Limits		Unit
	Typ.	Max.	
Block erase time	1.6	10	s
Block program time	0.6	2.1	s

Note 21: At $T_a = 25^\circ\text{C}$, $V_{pp} = 12\text{V}$

22: Byte/word program time is about $9 \mu\text{s}$ (typical), but not guaranteed.